

# Multilayer Power Inductor

## CIG21C Series (2012/ EIA 0805)



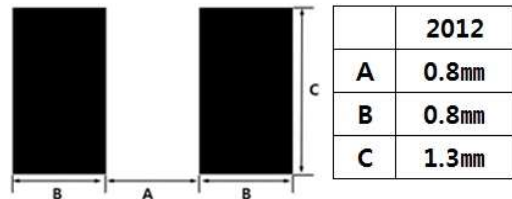
### APPLICATION

Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

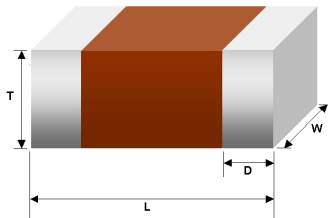
### FEATURES

- Suit for small DC-DC converter and choke uses
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability

### RECOMMENDED LAND PATTERN



### DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
21	2.0±0.1	1.25±0.1	0.9±0.1	0.5+0.2 -0.3

### DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG21C2R2MNE	0805/2012	2.2±20%	0.250±20 %	0.80
CIG21C4R7MNE	0805/2012	4.7±20%	0.433±20 %	0.58

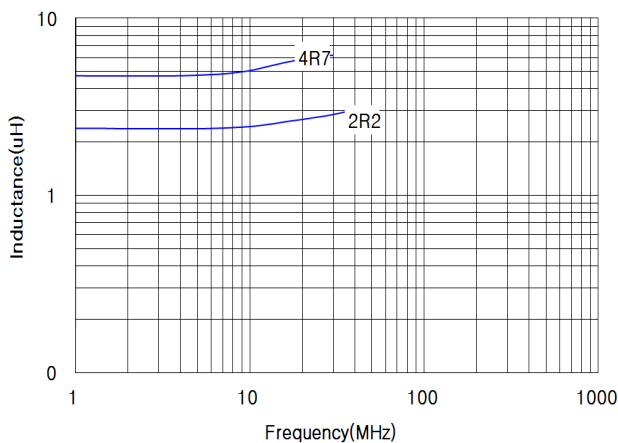
※Rated Current: DC current value when the self-generation of heat rises to 40°C (Reference ambient temperature:25°C)

※Operating temperature range: -40 to +125°C (Including self-temperature rise)

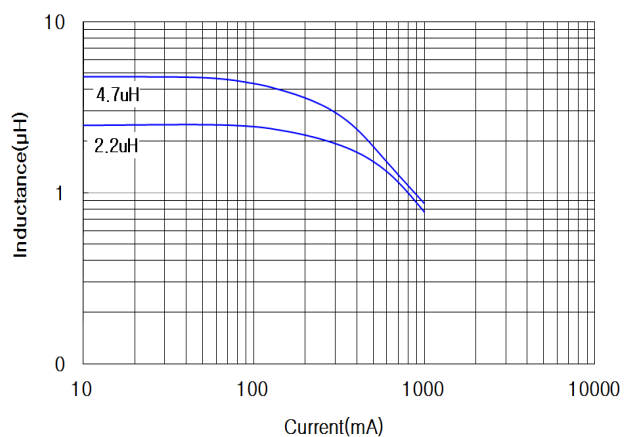
※Test equipment: Agilent :E4991A+16092A

### CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



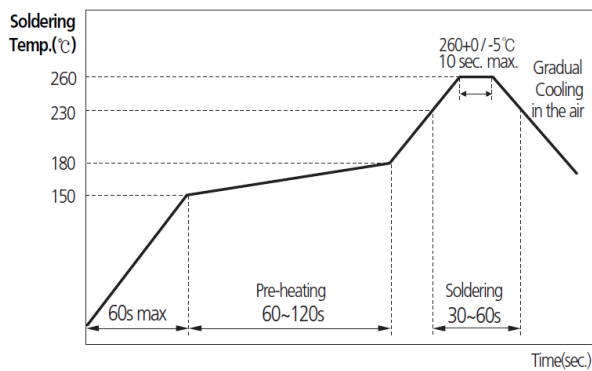
**PRODUCT IDENTIFICATION**

**CI G 21 C 2R2 M N E**  
**(1) (2) (3) (4) (5) (6) (7) (8)**

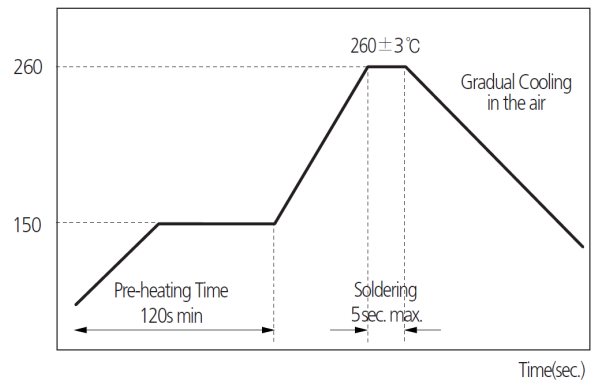
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (C:Choke Type)
- (5) Inductance (2R2:2.2uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

**RECOMMENDED SOLDERING CONDITION**

**REFLOW SOLDERING**



**FLOW SOLDERING**



**PACKAGING**

Packaging Style	Quantity(pcs/reel)
Embossed Taping	3,000

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.